A wide variety of die assembly methods and materials are available for implementation into high yield, high reliability systems. Some of the options for die seal and encapsulation are reviewed here for comparison.

**Hermetic – Seam Seal**

**Advantages:** hermetic, low temperature, large seal area, low profile, minimal floor space requirements

**Disadvantages:** low throughput

**Process Considerations:** dry box environment, electrode design, lid design

**Non-Hermetic – Glob Top**

**Advantages:** flexible, low temperature, low stress, low profile

**Disadvantages:** non-hermetic, limited protection, spread, wire wash potential

**Process Considerations:** dispensing parameters, viscosity, dams, cure